Infineon Technologies - XMC1301T016X0016AAXUMA1 Datasheet

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	ARM® Cortex®-M0
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, I²S, POR, PWM, WDT
Number of I/O	11
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 11x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	16-TSSOP (0.173", 4.40mm Width)
Supplier Device Package	PG-TSSOP-16-8
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/xmc1301t016x0016aaxuma1

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About this Document

This Data Sheet is addressed to embedded hardware and software developers. It provides the reader with detailed descriptions about the ordering designations, available features, electrical and physical characteristics of the XMC1300 series devices.

The document describes the characteristics of a superset of the XMC1300 series devices. For simplicity, the various device types are referred to by the collective term XMC1300 throughout this document.

XMC1000 Family User Documentation

The set of user documentation includes:

- **Reference Manual**
  – decribes the functionality of the superset of devices.
- **Data Sheets**
  – list the complete ordering designations, available features and electrical characteristics of derivative devices.
- **Errata Sheets**
  – list deviations from the specifications given in the related Reference Manual or Data Sheets. Errata Sheets are provided for the superset of devices.

Attention: Please consult all parts of the documentation set to attain consolidated knowledge about your device.

Application related guidance is provided by **Users Guides** and **Application Notes**.

Please refer to **http://www.infineon.com/xmc1000** to get access to the latest versions of those documents.

Table 4 XMC1300 Chip Identification Number

Derivative	Value	Marking
XMC1301-T016F0008	00013032 01CF00FF 00001FF7 0000100F 00000B00 00001000 00003000 $101ED083_H$	AA
XMC1301-T016F0016	00013032 01CF00FF 00001FF7 0000100F 00000B00 00001000 00005000 $101ED083_H$	AA
XMC1301-T016X0008	00013033 01CF00FF 00001FF7 0000100F 00000B00 00001000 00003000 $101ED083_H$	AA
XMC1301-T016X0016	00013033 01CF00FF 00001FF7 0000100F 00000B00 00001000 00005000 $101ED083_H$	AA
XMC1302-T016X0008	00013033 01FF00FF 00001FF7 0000900F 00000B00 00001000 00003000 $101ED083_H$	AA
XMC1302-T016X0016	00013033 01FF00FF 00001FF7 0000900F 00000B00 00001000 00005000 $101ED083_H$	AA
XMC1302-T016X0032	00013033 01FF00FF 00001FF7 0000900F 00000B00 00001000 00009000 $101ED083_H$	AA
XMC1301-T038F0008	00013012 01CF00FF 00001FF7 0000100F 00000B00 00001000 00003000 $101ED083_H$	AA
XMC1301-T038F0016	00013012 01CF00FF 00001FF7 0000100F 00000B00 00001000 00005000 $101ED083_H$	AA
XMC1301-T038F0032	00013012 01CF00FF 00001FF7 0000100F 00000B00 00001000 00009000 $101ED083_H$	AA
XMC1302-T038X0016	00013013 01FF00FF 00001FF7 0000900F 00000B00 00001000 00005000 $101ED083_H$	AA
XMC1302-T038X0032	00013013 01FF00FF 00001FF7 0000900F 00000B00 00001000 00009000 $101ED083_H$	AA
XMC1302-T038X0064	00013013 01FF00FF 00001FF7 0000900F 00000B00 00001000 00011000 $101ED083_H$	AA
XMC1302-T038X0128	00013013 01FF00FF 00001FF7 0000900F 00000B00 00001000 00021000 $101ED083_H$	AA
XMC1302-T038X0200	00013013 01FF00FF 00001FF7 0000900F 00000B00 00001000 00033000 $101ED083_H$	AA
XMC1301-Q024F0008	00013062 01CF00FF 00001FF7 0000100F 00000B00 00001000 00003000 $101ED083_H$	AA
XMC1301-Q024F0016	00013062 01CF00FF 00001FF7 0000100F 00000B00 00001000 00005000 $101ED083_H$	AA

2 General Device Information

This section summarizes the logic symbols and package pin configurations with a detailed list of the functional I/O mapping.

2.1 Logic Symbols

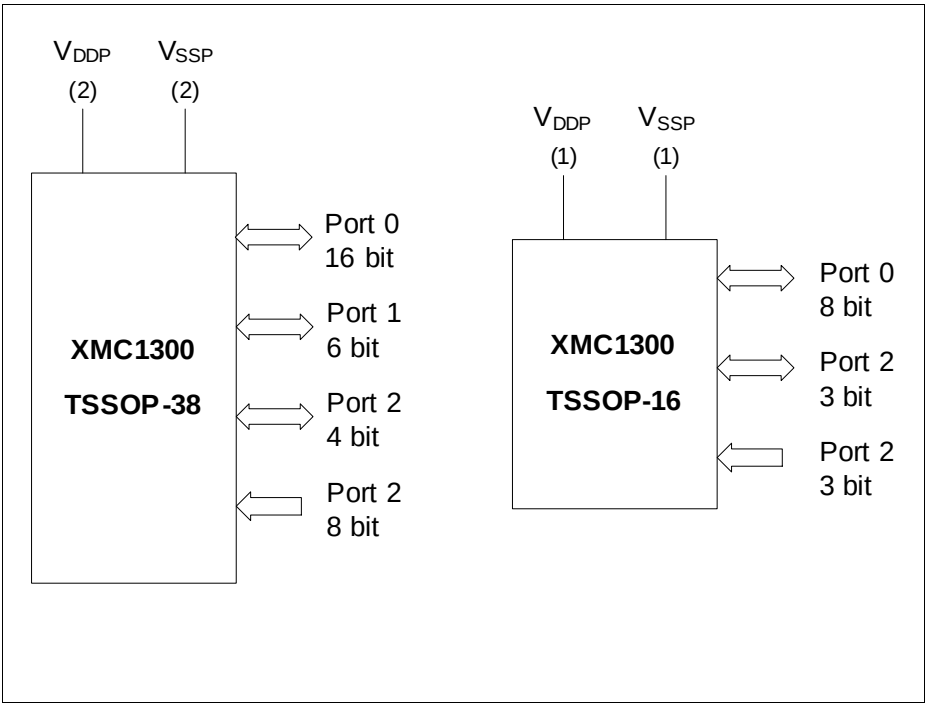

Figure 2 XMC1300 Logic Symbol for TSSOP-38 and TSSOP-16

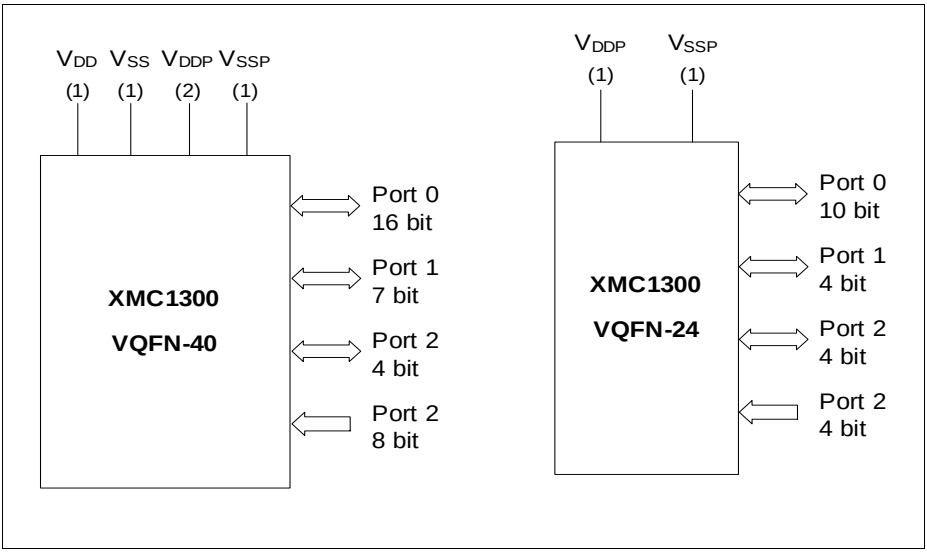

Figure 3 XMC1300 Logic Symbol for VQFN-24 and VQFN-40

2.2.1 Package Pin Summary

The following general building block is used to describe each pin:

Table 5 Package Pin Mapping Description

Function	Package A	Package B	...	Pad Type
Px.y	N	N		Pad Class

The table is sorted by the “Function” column, starting with the regular Port pins (Px.y), followed by the supply pins.

The following columns, titled with the supported package variants, lists the package pin number to which the respective function is mapped in that package.

The “Pad Type” indicates the employed pad type:

- STD_INOUT(standard bi-directional pads)
- STD_INOUT/AN (standard bi-directional pads with analog input)
- High Current (high current bi-directional pads)
- STD_IN/AN (standard input pads with analog input)
- Power (power supply)

Details about the pad properties are defined in the Electrical Parameters.

Table 6 Package Pin Mapping

Function	VQFN 40	TSSOP 38	VQFN 24	TSSOP 16	Pad Type	Notes
P0.0	23	17	15	7	STD_INOUT	
P0.1	24	18	-	-	STD_INOUT	
P0.2	25	19	-	-	STD_INOUT	
P0.3	26	20	-	-	STD_INOUT	
P0.4	27	21	-	-	STD_INOUT	
P0.5	28	22	16	8	STD_INOUT	
P0.6	29	23	17	9	STD_INOUT	
P0.7	30	24	18	10	STD_INOUT	
P0.8	33	27	19	11	STD_INOUT	
P0.9	34	28	20	12	STD_INOUT	
P0.10	35	29	-	-	STD_INOUT	
P0.11	36	30	-	-	STD_INOUT	
P0.12	37	31	21	-	STD_INOUT	

Table 6 Package Pin Mapping

Function	VQFN 40	TSSOP 38	VQFN 24	TSSOP 16	Pad Type	Notes
P0.13	38	32	22	-	STD_INOUT	
P0.14	39	33	23	13	STD_INOUT	
P0.15	40	34	24	14	STD_INOUT	
P1.0	22	16	14	-	High Current	
P1.1	21	15	13	-	High Current	
P1.2	20	14	12	-	High Current	
P1.3	19	13	11	-	High Current	
P1.4	18	12	-	-	High Current	
P1.5	17	11	-	-	High Current	
P1.6	16	-	-	-	STD_INOUT	
P2.0	1	35	1	15	STD_INOUT/AN	
P2.1	2	36	2	-	STD_INOUT/AN	
P2.2	3	37	3	-	STD_IN/AN	
P2.3	4	38	-	-	STD_IN/AN	
P2.4	5	1	-	-	STD_IN/AN	
P2.5	6	2	-	-	STD_IN/AN	
P2.6	7	3	4	16	STD_IN/AN	
P2.7	8	4	5	1	STD_IN/AN	
P2.8	9	5	5	1	STD_IN/AN	
P2.9	10	6	6	2	STD_IN/AN	
P2.10	11	7	7	3	STD_INOUT/AN	
P2.11	12	8	8	4	STD_INOUT/AN	
VSS	13	9	9	5	Power	Supply GND, ADC reference GND
VDD	14	10	10	6	Power	Supply VDD, ADC reference voltage/ ORC reference voltage. VDD has to be supplied with the same voltage as VDDP

Table 6 Package Pin Mapping

Function	VQFN 40	TSSOP 38	VQFN 24	TSSOP 16	Pad Type	Notes
VDDP	15	10	10	6	Power	I/O port supply
VSSP	31	25	-	-	Power	I/O port ground
VDDP	32	26	-	-	Power	I/O port supply
VSSP	Exp. Pad	-	Exp. Pad	-	Power	**Exposed Die Pad** The exposed die pad is connected internally to VSSP. For proper operation, it is mandatory to connect the exposed pad to the board ground. For thermal aspects, please refer to the Package and Reliability chapter.

Table 8 Port I/O Functions

Function	Outputs									Inputs											
	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	HWO0	HWO1	HWI0	HWI1	Input	Input	Input	Input	Input	Input	Input	Input	Input	Input
P0.0	ERU0.PDOUT0		ERU0.GOUT0	CCU40.OUT0	CCU80.OUT00	USIC0_CH0.SELO0	USIC0_CH1.SELO0					BCCU0.TRAPINB	CCU40.IN0C			USIC0_CH0.DX2A	USIC0_CH1.DX2A				
P0.1	ERU0.PDOUT1		ERU0.GOUT1	CCU40.OUT1	CCU80.OUT01	BCCU0.OUT8	SCU.VDROP						CCU40.IN1C								
P0.2	ERU0.PDOUT2		ERU0.GOUT2	CCU40.OUT2	CCU80.OUT02	VADC0.EMUX02	CCU80.OUT10						CCU40.IN2C								
P0.3	ERU0.PDOUT3		ERU0.GOUT3	CCU40.OUT3	CCU80.OUT03	VADC0.EMUX01	CCU80.OUT11						CCU40.IN3C								
P0.4	BCCU0.OUT0			CCU40.OUT1	CCU80.OUT13	VADC0.EMUX00	WWDT.SERVICE_OUT						CCU80.IN0B								
P0.5	BCCU0.OUT1			CCU40.OUT0	CCU80.OUT12	ACMP2.OUT	CCU80.OUT01						CCU80.IN1B								
P0.6	BCCU0.OUT2			CCU40.OUT0	CCU80.OUT11	USIC0_CH1.MCLKOUT	USIC0_CH1.DOUT0						CCU40.IN0B			USIC0_CH1.DX0C					
P0.7	BCCU0.OUT3			CCU40.OUT1	CCU80.OUT10	USIC0_CH0.SCLKOUT	USIC0_CH1.DOUT0						CCU40.IN1B			USIC0_CH0.DX1C	USIC0_CH1.DX0D	USIC0_CH1.DX1C			
P0.8	BCCU0.OUT4			CCU40.OUT2	CCU80.OUT20	USIC0_CH0.SCLKOUT	USIC0_CH1.SCLKOUT						CCU40.IN2B			USIC0_CH0.DX1B	USIC0_CH1.DX1B				
P0.9	BCCU0.OUT5			CCU40.OUT3	CCU80.OUT21	USIC0_CH0.SELO0	USIC0_CH1.SELO0						CCU40.IN3B			USIC0_CH0.DX2B	USIC0_CH1.DX2B				
P0.10	BCCU0.OUT6			ACMP0.OUT	CCU80.OUT22	USIC0_CH0.SELO1	USIC0_CH1.SELO1						CCU80.IN2B			USIC0_CH0.DX2C	USIC0_CH1.DX2C				
P0.11	BCCU0.OUT7			USIC0_CH0.MCLKOUT	CCU80.OUT23	USIC0_CH0.SELO2	USIC0_CH1.SELO2									USIC0_CH0.DX2D	USIC0_CH1.DX2D				
P0.12	BCCU0.OUT6				CCU80.OUT33	USIC0_CH0.SELO3	CCU80.OUT20					BCCU0.TRAPINA	CCU40.IN0A	CCU40.IN1A	CCU40.IN2A	CCU40.IN3A	CCU80.IN0A	CCU80.IN1A	CCU80.IN2A	CCU80.IN3A	USIC0_CH0.DX2E
P0.13	WWDT.SERVICE_OUT				CCU80.OUT32	USIC0_CH0.SELO4	CCU80.OUT21						CCU80.IN3B	POSIF0.IN0B		USIC0_CH0.DX2F					
P0.14	BCCU0.OUT7				CCU80.OUT31	USIC0_CH0.DOUT0	USIC0_CH0.SCLKOUT							POSIF0.IN1B		USIC0_CH0.DX0A	USIC0_CH0.DX1A				
P0.15	BCCU0.OUT8				CCU80.OUT30	USIC0_CH0.DOUT0	USIC0_CH1.MCLKOUT							POSIF0.IN2B		USIC0_CH0.DX0B					
P1.0	BCCU0.OUT0	CCU40.OUT0			CCU80.OUT00	ACMP1.OUT	USIC0_CH0.DOUT0		USIC0_CH0.DOUT0		USIC0_CH0.HWIN0			POSIF0.IN2A		USIC0_CH0.DX0C					
P1.1	VADC0.EMUX00	CCU40.OUT1			CCU80.OUT01	USIC0_CH0.DOUT0	USIC0_CH1.SELO0		USIC0_CH0.DOUT1		USIC0_CH0.HWIN1			POSIF0.IN1A		USIC0_CH0.DX0D	USIC0_CH0.DX1D	USIC0_CH1.DX2E			
P1.2	VADC0.EMUX01	CCU40.OUT2			CCU80.OUT10	ACMP2.OUT	USIC0_CH1.DOUT0		USIC0_CH0.DOUT2		USIC0_CH0.HWIN2			POSIF0.IN0A		USIC0_CH1.DX0B					
P1.3	VADC0.EMUX02	CCU40.OUT3			CCU80.OUT11	USIC0_CH1.SCLKOUT	USIC0_CH1.DOUT0		USIC0_CH0.DOUT3		USIC0_CH0.HWIN3					USIC0_CH1.DX0A	USIC0_CH1.DX1A				
P1.4	VADC0.EMUX10	USIC0_CH1.SCLKOUT			CCU80.OUT20	USIC0_CH0.SELO0	USIC0_CH1.SELO1									USIC0_CH0.DX5E	USIC0_CH1.DX5E				
P1.5	VADC0.EMUX11	USIC0_CH0.DOUT0		BCCU0.OUT1	CCU80.OUT21	USIC0_CH0.SELO1	USIC0_CH1.SELO2									USIC0_CH1.DX5F					

Table 8 Port I/O Functions (cont'd)

Function	Outputs									Inputs										
	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	HWO0	HWO1	HWI0	HWI1	Input	Input	Input	Input	Input	Input	Input	Input	Input
P1.6	VADC0. EMUX12	USIC0_CH1 .DOUT0		USIC0_CH0 .SCLKOUT	BCCU0. OUT2	USIC0_CH0 .SELO2	USIC0_CH1 .SELO3							USIC0_CH0 .DX5F						
P2.0	ERU0. PDOUT3	CCU40. OUT0	ERU0. GOUT3		CCU80. OUT20	USIC0_CH0 .DOUT0	USIC0_CH0 .SCLKOUT						VADC0. G0CH5		ERU0.0B0	USIC0_CH0 .DX0E	USIC0_CH0 .DX1E	USIC0_CH1 .DX2F			
P2.1	ERU0. PDOUT2	CCU40. OUT1	ERU0. GOUT2		CCU80. OUT21	USIC0_CH0 .DOUT0	USIC0_CH1 .SCLKOUT					ACMP2.INP	VADC0. G0CH6		ERU0.1B0	USIC0_CH0 .DX0F	USIC0_CH1 .DX3A	USIC0_CH1 .DX4A			
P2.2												ACMP2.INN	VADC0. G0CH7		ERU0.0B1	USIC0_CH0 .DX3A	USIC0_CH0 .DX4A	USIC0_CH1 .DX5A	ORC0.AIN		
P2.3													VADC0. G1CH5		ERU0.1B1	USIC0_CH0 .DX5B	USIC0_CH1 .DX3C	USIC0_CH1 .DX4C	ORC1.AIN		
P2.4													VADC0. G1CH6		ERU0.0A1	USIC0_CH0 .DX3B	USIC0_CH0 .DX4B	USIC0_CH1 .DX5B	ORC2.AIN		
P2.5													VADC0. G1CH7		ERU0.1A1	USIC0_CH0 .DX5D	USIC0_CH1 .DX3E	USIC0_CH1 .DX4E	ORC3.AIN		
P2.6												ACMP1.INN	VADC0. G0CH0		ERU0.2A1	USIC0_CH0 .DX3E	USIC0_CH0 .DX4E	USIC0_CH1 .DX5D	ORC4.AIN		
P2.7												ACMP1.INP	VADC0. G1CH1		ERU0.3A1	USIC0_CH0 .DX5C	USIC0_CH1 .DX3D	USIC0_CH1 .DX4D	ORC5.AIN		
P2.8												ACMP0.INN	VADC0. G0CH1	VADC0. G1CH0	ERU0.3B1	USIC0_CH0 .DX3D	USIC0_CH0 .DX4D	USIC0_CH1 .DX5C	ORC6.AIN		
P2.9												ACMP0.INP	VADC0. G0CH2	VADC0. G1CH4	ERU0.3B0	USIC0_CH0 .DX5A	USIC0_CH1 .DX3B	USIC0_CH1 .DX4B	ORC7.AIN		
P2.10	ERU0. PDOUT1	CCU40. OUT2	ERU0. GOUT1		CCU80. OUT30	ACMP0. OUT	USIC0_CH1 .DOUT0						VADC0. G0CH3	VADC0. G1CH2	ERU0.2B0	USIC0_CH0 .DX3C	USIC0_CH0 .DX4C	USIC0_CH1 .DX0F			
P2.11	ERU0. PDOUT0	CCU40. OUT3	ERU0. GOUT0		CCU80. OUT31	USIC0_CH1 .SCLKOUT	USIC0_CH1 .DOUT0					ACMP.REF	VADC0. G0CH4	VADC0. G1CH3	ERU0.2B1	USIC0_CH1 .DX0E	USIC0_CH1 .DX1E				

3.1.3 Operating Conditions

The following operating conditions must not be exceeded in order to ensure correct operation and reliability of the XMC1300. All parameters specified in the following tables refer to these operating conditions, unless noted otherwise.

Table 10 Operating Conditions Parameters

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Ambient Temperature	T_A SR	-40	–	85	°C	Temp. Range F
		-40	–	105	°C	Temp. Range X
Digital supply voltage[1)]	V_{DDP} SR	1.8	–	5.5	V	
MCLK Frequency	f_{MCLK} CC	–	–	33.2	MHz	CPU clock
PCLK Frequency	f_{PCLK} CC	–	–	66.4	MHz	Peripherals clock

1) See also the Supply Monitoring thresholds, **Chapter 3.3.3**.

Table 11 Input/Output Characteristics (Operating Conditions apply) (cont'd)

Parameter	Symbol		Limit Values		Unit	Test Conditions
			Min.	Max.		
Maximum current into V_{DDP} (TSSOP16, VQFN24)	I_{MVDD1}	SR	–	130	mA	3)
Maximum current into V_{DDP} (TSSOP38, VQFN40)	I_{MVDD2}	SR	–	260	mA	3)
Maximum current out of V_{SS} (TSSOP16, VQFN24)	I_{MVSS1}	SR	–	130	mA	3)
Maximum current out of V_{SS} (TSSOP38, VQFN40)	I_{MVSS2}	SR	–	260	mA	3)

1) Not subject to production test, verified by design/characterization. Hysteresis is implemented to avoid meta stable states and switching due to internal ground bounce. It cannot be guaranteed that it suppresses switching due to external system noise.

2) An additional error current (I_{INJ}) will flow if an overload current flows through an adjacent pin.

3) Not subject to production test, verified by design/characterization.

4) Not subject to production test, verified by design/characterization. However, for applications with strict low power-down current requirements, it is mandatory that no active voltage source is supplied at any GPIO pin when V_{DDP} is powered off.

Table 17 provides the active current consumption of some modules operating at 5 V power supply at 25 °C. The typical values shown are used as a reference guide on the current consumption when these modules are enabled.

Table 17 Typical Active Current Consumption[1)]

Active Current Consumption	Symbol	Limit Values	Unit	Test Condition
		Typ.		
Baseload current	I_{CPUDDC}	5.04	mA	Modules including Core, SCU, PORT, memories, ANATOP[2)]
VADC and SHS	I_{ADCDDC}	3.4	mA	Set CGATCLR0.VADC to 1[3)]
USIC0	$I_{USIC0DDC}$	0.87	mA	Set CGATCLR0.USIC0 to 1[4)]
CCU40	$I_{CCU40DDC}$	0.94	mA	Set CGATCLR0.CCU40 to 1[5)]
CCU80	$I_{CCU80DDC}$	0.42	mA	Set CGATCLR0.CCU80 to 1[6)]
POSIF0	$I_{PIF0DDC}$	0.26	mA	Set CGATCLR0.POSIF0 to 1[7)]
BCCU0	$I_{BCCU0DDC}$	0.24	mA	Set CGATCLR0.BCCU0 to 1[8)]
MATH	$I_{MATHDDC}$	0.35	mA	Set CGATCLR0.MATH to 1[9)]
WDT	I_{WDTDDC}	0.03	mA	Set CGATCLR0.WDT to 1[10)]
RTC	I_{RTCDDC}	0.01	mA	Set CGATCLR0.RTC to 1[11)]

1) Not subject to production test, verified by design/characterisation.

2) Baseload current is measured with device running in user mode, MCLK=PCLK=32 MHz, with an endless loop in the flash memory. The clock to the modules stated in CGATSTAT0 are gated.

3) Active current is measured with: module enabled, MCLK=32 MHz, running in auto-scan conversion mode

4) Active current is measured with: module enabled, alternating messages sent to PC at 57.6kbaud every 200ms

5) Active current is measured with: module enabled, MCLK=PCLK=32 MHz, 1 CCU4 slice for PWM switching from 1500Hz and 1000Hz at regular intervals, 1 CCU4 slice in capture mode for reading period and duty cycle

6) Active current is measured with: module enabled, MCLK=PCLK=32 MHz, 1 CCU8 slice with PWM frequency at 1500Hz and a period match interrupt used to toggle duty cycle between 10% and 90%

7) Active current is measured with: module enabled, MCLK=32 MHz, PCLK=64MHz, hall sensor mode

8) Active current is measured with: module enabled, MCLK=32 MHz, PCLK=64MHz, FCLK=0.8MHz, Normal mode (BCCU Clk = FCLK/4), 3 BCCU Channels and 1 Dimming Engine, change color or dim every 1s

9) Active current is measured with: module enabled, MCLK=32 MHz, PCLK=64MHz, tangent calculation in while loop; CORDIC circular rotation, no keep, autostart; 32-by-32 bit signed DIV, autostart, DVS right shift by 11

10) Active current is measured with: module enabled, MCLK=32 MHz, time-out mode; WLB = 0, WUB = 0x00008000; WDT serviced every 1s

11) Active current is measured with: module enabled, MCLK=32 MHz, Periodic interrupt enabled

3.2.7 Flash Memory Parameters

Note: These parameters are not subject to production test, but verified by design and/or characterization.

Table 18 Flash Memory Parameters

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Erase Time per page	t_{ERASE} CC	6.8	7.1	7.6	ms	
Program time per block	t_{PSER} CC	102	152	204	µs	
Wake-Up time	t_{WU} CC	–	32.2	–	µs	
Read time per word	t_a CC	–	50	–	ns	
Data Retention Time	t_{RET} CC	10	–	–	years	Max. 100 erase / program cycles
Flash Wait States [1]	$N_{WSFLASH}$ CC	0	0.5	–		f_{MCLK} = 8 MHz
		0	1.4	–		f_{MCLK} = 16 MHz
		1	1.9	–		f_{MCLK} = 32 MHz
Erase Cycles per page	N_{ECYC} CC	–	–	$5*10^4$	cycles	
Total Erase Cycles	N_{TECYC} CC	–	–	$2*10^6$	cycles	

1) Flash wait states are automatically inserted by the Flash module during memory read when needed. Typical values are calculated from the execution of the Dhrystone benchmark program.

3.3.4 On-Chip Oscillator Characteristics

Table 21 provides the characteristics of the 64 MHz clock output from the digital controlled oscillator, DCO1 in XMC1300.

Table 21 64 MHz DCO1 Characteristics (Operating Conditions apply)

Parameter	Symbol		Limit Values			Unit	Test Conditions
			Min.	Typ.	Max.		
Nominal frequency	f_{NOM}	CC	63.5	64	64.5	MHz	under nominal conditions[1] after trimming
Accuracy	Δf_{LT}	CC	-1.7	–	3.4	%	with respect to f_{NOM}(typ), over temperature (T_A = 0 °C to 85 °C)[2]
			-3.9	–	4.0	%	with respect to f_{NOM}(typ), over temperature (T_A = -40 °C to 105 °C)[2]
Accuracy with calibration based on temperature sensor	Δf_{LTT}	CC	-1.3	–	1.25	%	with respect to f_{NOM}(typ), over temperature (T_A = 0 °C to 105 °C)[2]
			-2.6	–	1.25	%	with respect to f_{NOM}(typ), over temperature (T_A = -40 °C to 105 °C)[2]

1) The deviation is relative to the factory trimmed frequency at nominal V_{DDC} and T_A = + 25 °C.

2) Not subject to production test, verified by design/characterisation.

3.3.6 SPD Timing Requirements

The optimum SPD decision time between 0_B and 1_B is 0.75 µs. With this value the system has maximum robustness against frequency deviations of the sampling clock on tool and on device side. However it is not always possible to exactly match this value with the given constraints for the sample clock. For instance for a oversampling rate of 4, the sample clock will be 8 MHz and in this case the closest possible effective decision time is 5.5 clock cycles (0.69 µs).

Table 24 Optimum Number of Sample Clocks for SPD

Sample Freq.	Sampling Factor	Sample Clocks 0_B	Sample Clocks 1_B	Effective Decision Time[1)]	Remark
8 MHz	4	1 to 5	6 to 12	0.69 µs	The other closest option (0.81 µs) for the effective decision time is less robust.

1) Nominal sample frequency period multiplied with 0.5 + (max. number of 0_B sample clocks)

For a balanced distribution of the timing robustness of SPD between tool and device, the timing requirements for the tool are:

- Frequency deviation of the sample clock is +/- 5%
- Effective decision time is between 0.69 µs and 0.75 µs (calculated with nominal sample frequency)

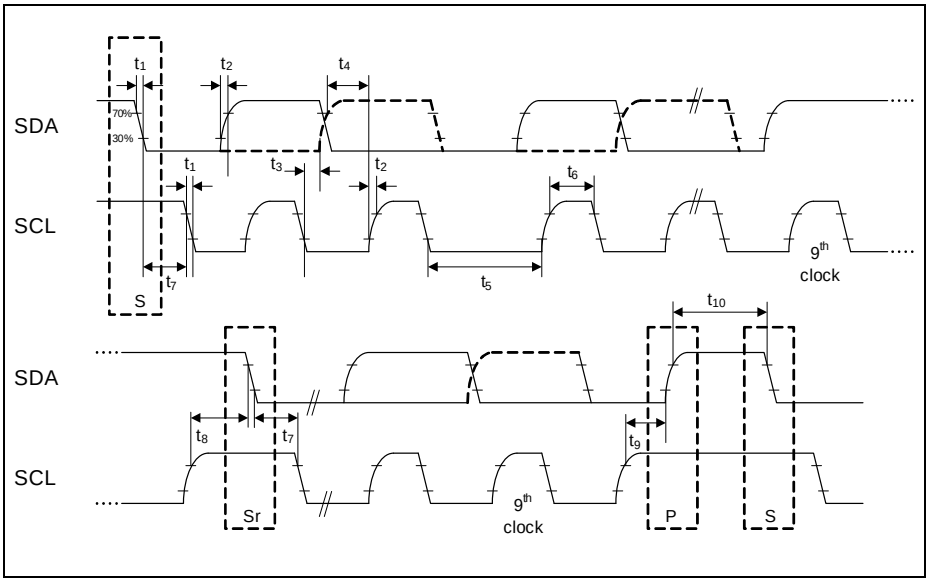

Figure 17 USIC IIC Stand and Fast Mode Timing

3.3.7.3 Inter-IC Sound (IIS) Interface Timing

The following parameters are applicable for a USIC channel operated in IIS mode.

Note: Operating Conditions apply.

Table 29 USIC IIS Master Transmitter Timing

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Clock period	t_1 CC	$2/f_{MCLK}$	-	-	ns	$V_{DDP} \geq 3$ V
		$4/f_{MCLK}$	-	-	ns	$V_{DDP} < 3$ V
Clock HIGH	t_2 CC	0.35 x t_{1min}	-	-	ns	
Clock Low	t_3 CC	0.35 x t_{1min}	-	-	ns	
Hold time	t_4 CC	0	-	-	ns	
Clock rise time	t_5 CC	-	-	0.15 x t_{1min}	ns	

4.2 Package Outlines

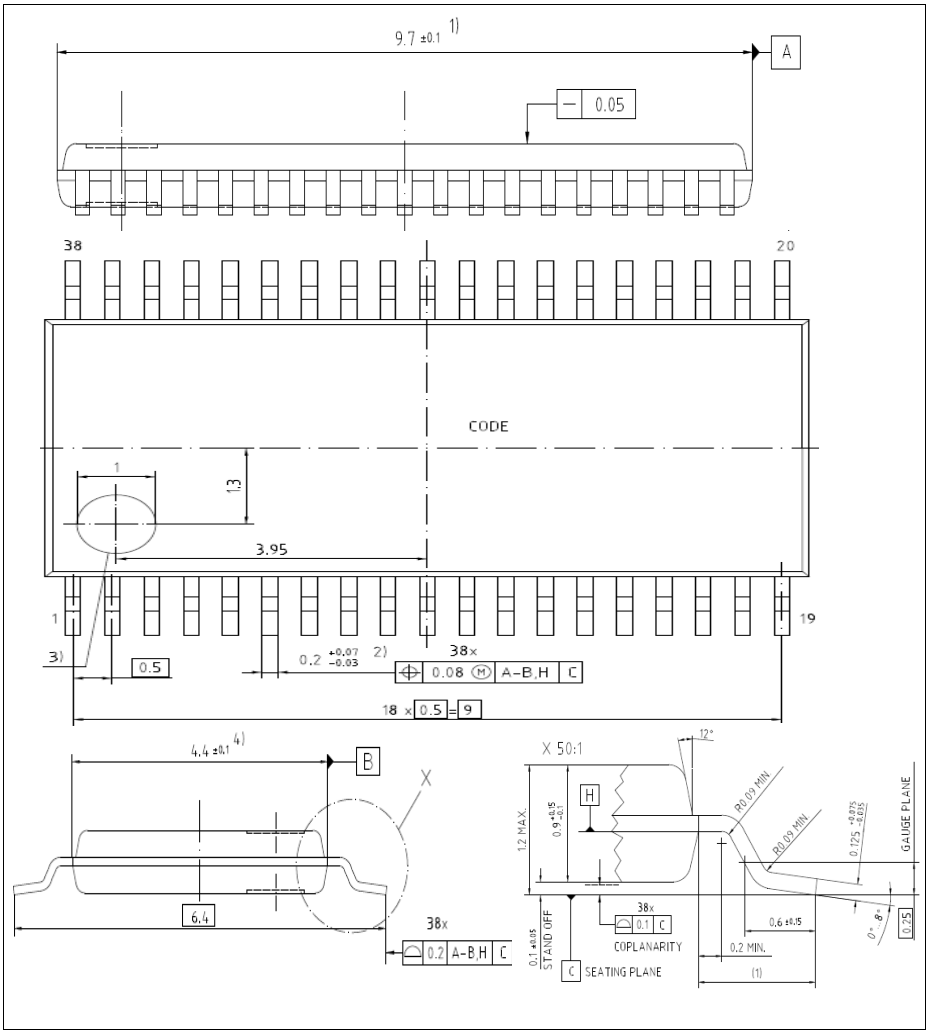

Figure 20 PG-TSSOP-38-9

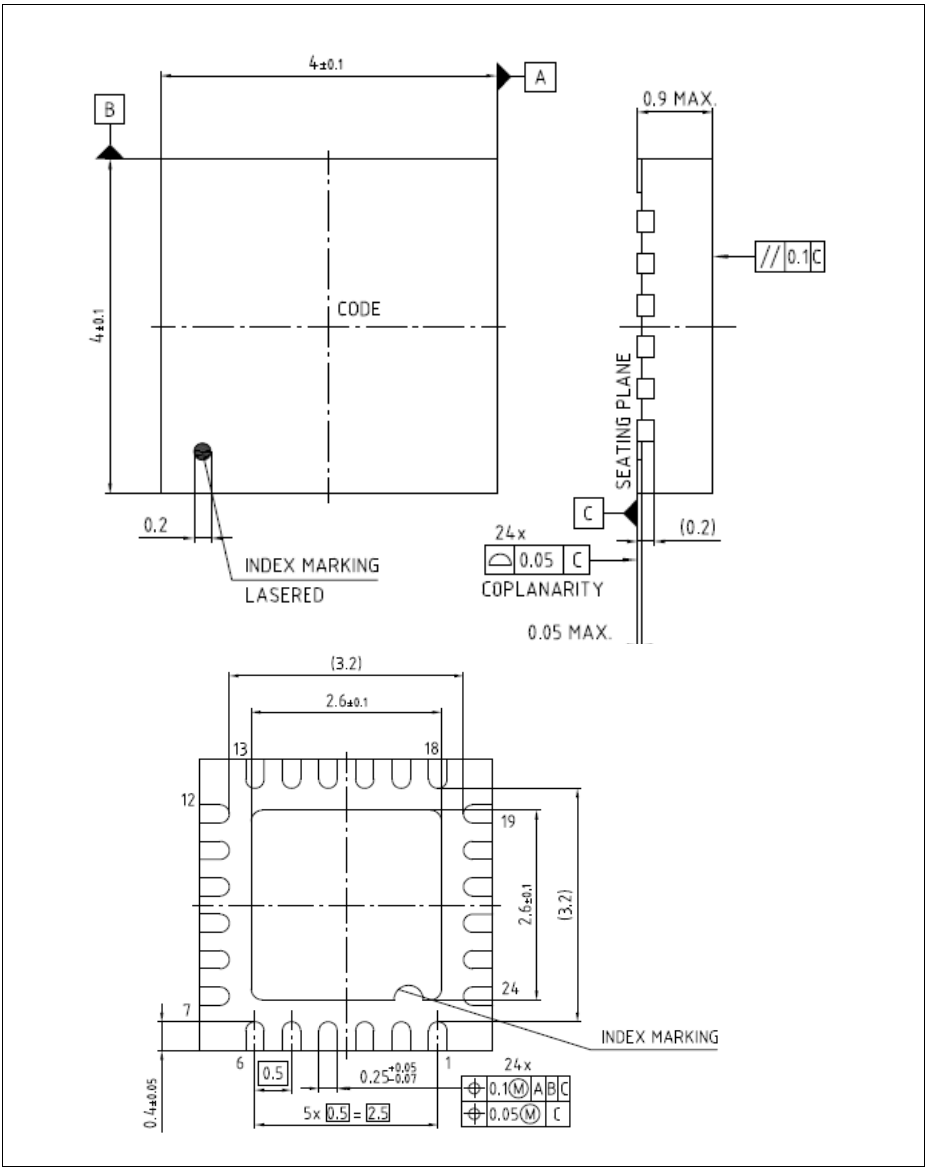

Figure 22 PG-VQFN-24-19

5 Quality Declaration

Table 32 shows the characteristics of the quality parameters in the XMC1300.

Table 32 Quality Parameters

Parameter	Symbol	Limit Values		Unit	Notes
		Min.	Max.		
ESD susceptibility according to Human Body Model (HBM)	V_{HBM} SR	-	2000	V	Conforming to EIA/JESD22-A114-B
ESD susceptibility according to Charged Device Model (CDM) pins	V_{CDM} SR	-	500	V	Conforming to JESD22-C101-C
Moisture sensitivity level	MSL CC	-	3	-	JEDEC J-STD-020C